



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

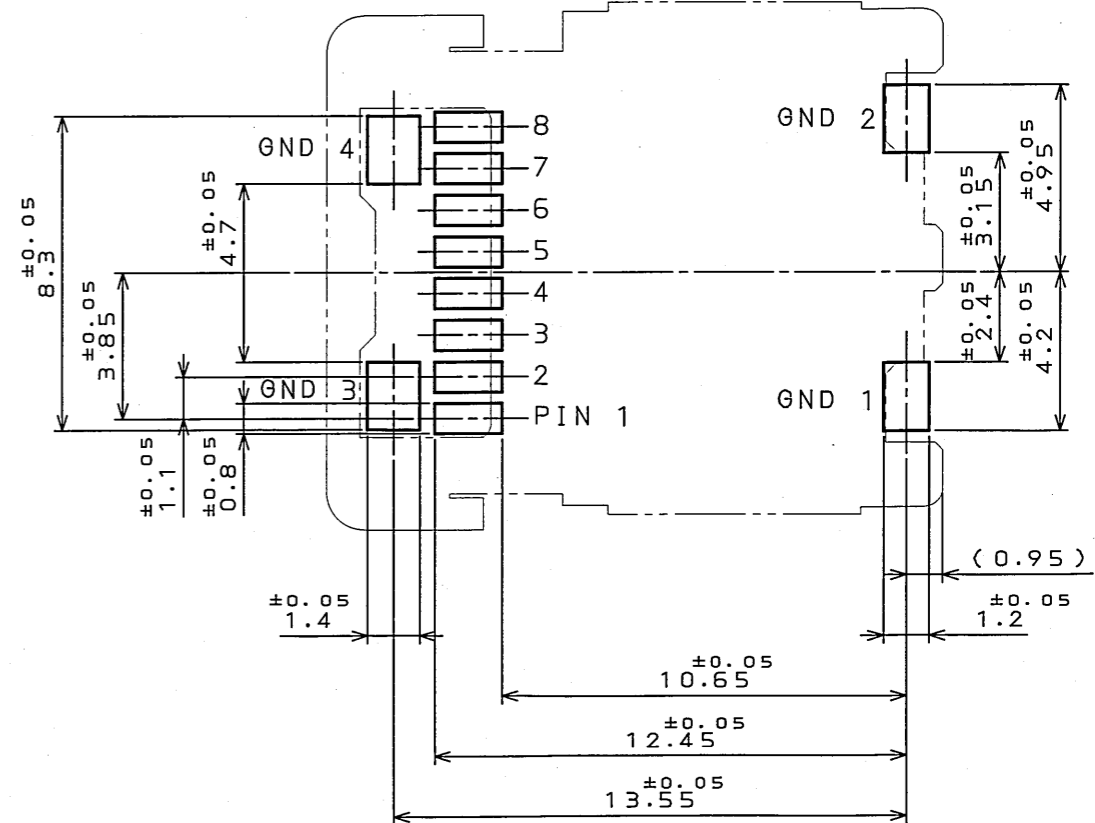
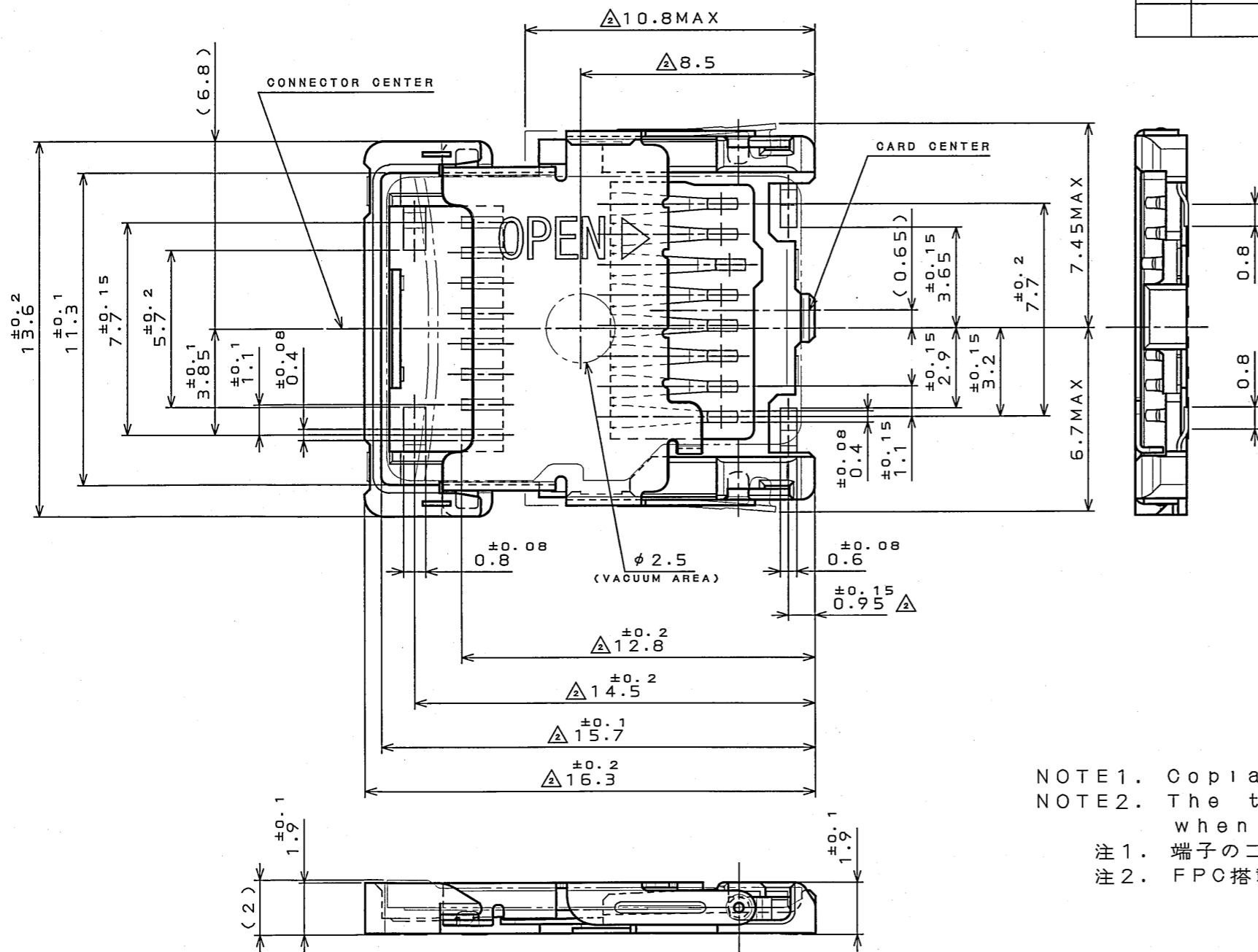
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



図面番号(DRAWING NO.) SJ104204

| 版数 REV. | 年月日 DATE | DCN NO. | 変更内容 DESCRIPTION | 製図 DR. | 担当 CHK. | 査閲 APPD. | 承認 APPD. |
|---------|-------------|---------|------------------|--------|-----------|----------|----------|
| 2 | 16.Jun.2005 | 057609 | CHANGED FORM | | M.SHIMADA | | A.Natori |



APPLICABLE P.C.B. DIMENSION(REF.)
適合基板寸法(参考)

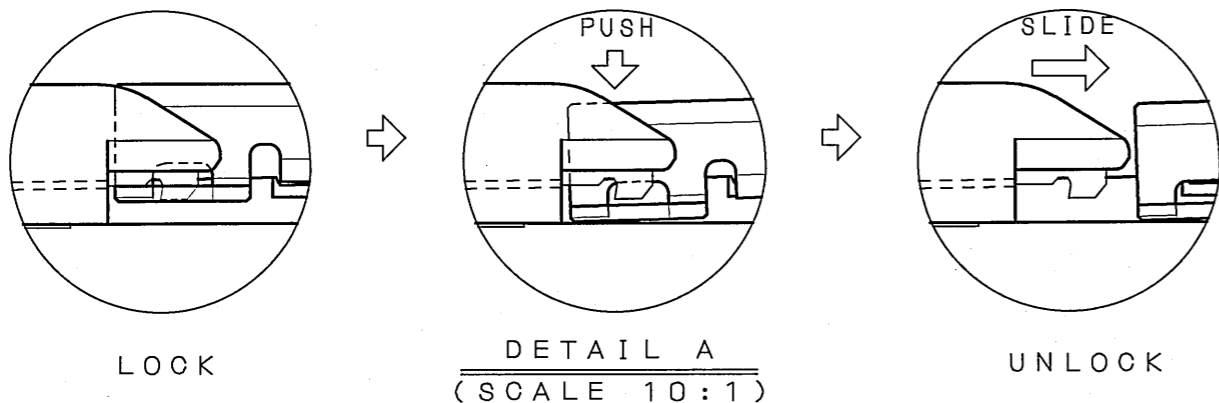
NOTE1. Coplanarity of all terminals should be 0.1mm MAX.
NOTE2. The thickness of reinforcement board is 0.6MIN, when the product will mount on FPC.

注1. 端子のコプラリティは0.1以下とする。
注2. FPC搭載時の補強版厚さは0.6以上とする。

| CONTACT AREA (CARD SIDE) | TERMINAL AREA (P.W.B SIDE) | HINGE AREA |
|-------------------------------|-------------------------------|-------------------------------|
| Au (0.5μm min) OVER NI(2~6μm) | Au(0.03~0.2μm) OVER NI(2~6μm) | Au(0.03~0.2μm) OVER NI(2~6μm) |

| 序号 NO. | 名称 DESCRIPTION | 個数 QTY. | 材料 MATERIAL | 仕上 FINISH | 備考 REMARKS |
|--------|----------------|---------|-----------------|--------------------|-------------------------|
| 3 | COVER | 1 | STAINLESS STEEL | | |
| 2 | HOUSING | 1 | 35% GF LCP | | UL94 V-0 COLOR:BLACK |
| 1 | CONTACT | 8 | PHOSPHOR BRONZE | Au OVER NI(TABLE1) | |

| | | | | | | | | | |
|--------------------------|--|--------------------|--|-----------|--|--------------|--|---|--|
| 仕様書(SPECIFICATION) | | 第1版(ORIGINAL DATE) | | 尺度(SCALE) | | シリーズ(SERIES) | | 日本航空電子工業株式会社 | |
| JACS-10275 | | 27.Apr.2005 | | 5:1 | | ST1 | | JAPAN AVIATION ELECTRONICS INDUSTRY, LTD. | |
| 一般公差(GENERAL TOLERANCE) | | 製図 DR. | | 名称(TITLE) | | ST1W008S4A | | 図面番号(DRAWING NO.) SJ104204 | |
| 寸法(DIMENSION) 角度(ANGLES) | | 担当 CHK. | | M.SHIMADA | | | | | |
| . ±0.8 | | 査閲 APPD. | | | | | | | |
| .X ±0.4 | | 承認 APPD. | | A.NATORI | | 質量(MASS) | | 版数 (REV.) 2 | |
| .XX ±0.1 | | | | | | | | | |
| .XXX ± | | | | | | | | | |



DOF-0-212E(03.08)

